

### SPECIFICATIONS:

<b>ELECTRICAL:</b>	
RATED CURRENT:	5A
RATED VOLTAGE:	300VDC
WITHSTANDING VOLTAGE:	500VAC (rms) FOR 1 MIN
INSULATION RESISTANCE:	> 1,000 mΩ at 500VDC
CONTACT RESISTANCE:	13mOhms MAX
DIELECTRIC STRENGTH:	1000VAC FOR 1 MIN
OPERATING TEMPERATURE:	-55°C TO +105°C
<b>MATERIALS:</b>	
SHELL:	NICKEL PLATED STEEL
BRACKET:	NICKEL PLATED STEEL
INSULATOR:	NYLON 6T, UL 94V-0, BLACK
PROCESS TEMP:	260°C
INSULATOR:	PATONE #322C, COLOR=Pc99
CONTACT:	TIN PLATED PHOSPHOR BRONZE
	MATING AREA (SEE P/N KEY)
	TIN PLATED PCB SOLDER AREA

### Storage and Process Instructions:

For parts exposed to greater than 60% RH, it is recommended parts be baked at 125°C for 3-5 hours prior to SMT reflow process. If unsure of RH exposure, it is recommend to bake at the above temperature and time prior to SMT reflow process.

## 190-025-263R00Y

CONTACT PLATING (MATING AREA):  
1 = GOLD FLASH  
2 = 30µ" GOLD

UNITS = inch [mm]

DO NOT SCALE FROM DRAWING



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DRAWN:

C. SMITH

DATE:

04/14/2009

# NorComp

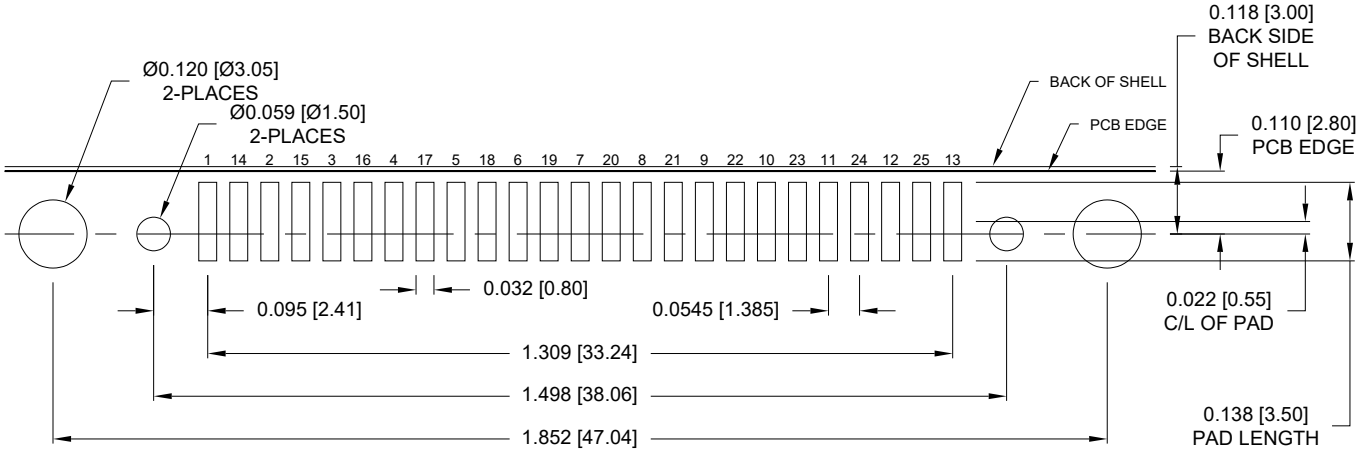
SCALE:  
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SHEET OF  
1 2

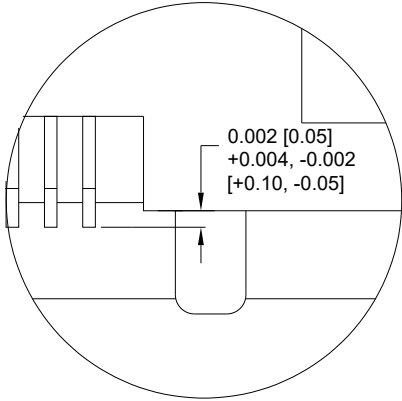
REV  
13

DWG NO.

190-025-263R001



RECOMMENDED PCB LAYOUT

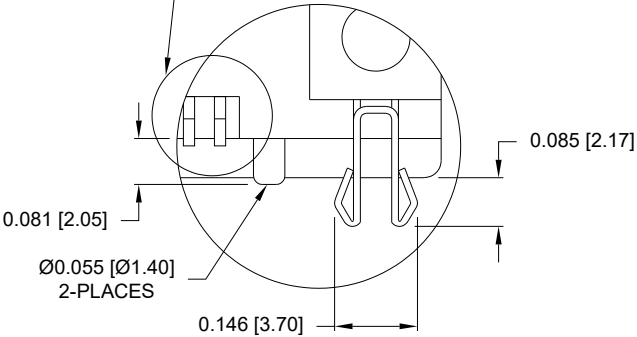


DETAIL "B"  
CONTACT COPLANARITY

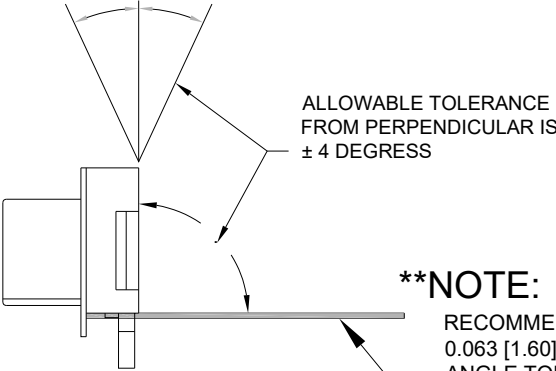
CONTACT ARRANGEMENT

1 14 2 15 3 16 4 17 5 18 6 19 7 20 8 21 9 22 10 23 11 24 12 25 13

SEE DETAIL "B"  
FOR CONTACT  
COPLANARITY



DETAIL "A"



RoHS COMPLIANT



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SHEET 2 OF 2

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